



Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
(503) 268-8000

Package: 24 PDIP with Matte Sn Plating
Total Device Weight 1.92 Grams

August, 2008	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	0.49%	0.009			Silicon chip	7440-21-3	Die size: 3.0 x 2.7 mm
Mold	72.62%	1.394	62.24%	1.195	Silica Fused	60676-86-0	Mold Compound Density between 2.0 and 2.2 grams/cc 75 to 95% Silica Fused (LSC uses 85.7% in our calculation) 2 to 8% Epoxy Resin (LSC uses 6% in our calculation). 2 to 8% Phenol Resin (LSC uses 6% in our calculation) 1 to 3% Cresol Novolac Epoxy (LSC uses 2% in our calculation). 0.1 to 0.5% Carbon black (LSC uses 0.3% in our calculation)
			4.36%	0.084	Epoxy Resin	-	
			4.36%	0.084	Phenol Resin	-	
			1.45%	0.028	Epoxy, Cresol Novolac	29690-82-2	
			0.22%	0.004	Carbon black	1333-86-4	
D/A Epoxy	0.04%	0.0008	0.03%	0.0005	Silver-filled epoxy	7440-22-4	Die attach epoxy Density: 4 grams/cc (silver content: 60-100%; LSC uses 80% in our calculation)
			0.02%	0.0003	Silver (Ag) other	-	
Wire	0.04%	0.0007			Gold (Au)	7440-57-5	1.00 mil diameter; 1 wire per package lead; wire length 3 mm
Lead Plating	1.72%	0.033			Tin (Sn)	7440-31-5	Plating is 100% Sn; thickness is 0.015mm
Leadframe	25.09%	0.482	24.45%	0.469	Copper (Cu)	7440-50-8	Leadframe thickness is nominal (per Case Outline) 97.46% Cu 2.35% Fe 0.12% Zn 0.07% P
			0.59%	0.011	Iron (Fe)	7439-89-6	
			0.03%	0.0006	Zinc (Zn)	7440-66-6	
			0.02%	0.0003	Phosphorus (P)	7723-14-0	

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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